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# Small-sized Class-D Speaker Amplifiers

# Analog Input Monaural Class-D Speaker Amplifier



No.10101EAT05

#### Description

BD5465GUL

BD5465GUL is a monaural Class-D speaker amplifier that contained ALC function for mobile phone, portable type electronic devices etc. LC filter of speaker output is not needed, can form monaural speaker amplifier with 3 external parts. ALC, short for Automatic Level Control, is a function that automatically adjusts up to the level of suppression of distortion (clip) of output wave form during excessive input. The output limit level uses a control type which doesn't follow up power supply. The time until the limit release operation of output level is called the release time (or recovery time). This IC adopts release time (560ms/1dB Typ.) and suits the applications which play music.

Through Class-D operation, efficiency is high low power consumption that is why it's suitable for battery drive application. The current consumption during shutdown when lowered to  $0.01\mu A(Typ.)$ , from the shutdown to the operation time is early and at the same time pop sound is few that is why it's also suitable in repeating active and shutdown.

#### ● Feature

- 1) Contains Digital ALC (Automatic Level Control) Function
- 2) External Parts: 3 points
- 3) Ultra slim type package: 9pin WL-CSP (1.8×1.8×0.55mmMax.)
- 4) BD5460 / 61GUL (No ALC Function, Gain Fixed Goods) Pin Compatible Specs BD5466 / 67 / 68GUL (ALC Function, Gain Fixed Goods) Pin Compatible Specs
- 5) Maximum Gain: 12 dB (Typ.) [during ALC operation, +12~-3dB@1dB Step]
- 6) ALC limit level control type: Fixed type doesn't follow up power supply
- 7) Limit output power: 0.6W (Typ.) [VDD= $3.4 \sim 5.5 \text{V}$ , RL= $8\Omega$ ]
- 8) ALC release (recovery) time: 560ms/1dB (Typ.)
- 9) Audio Analog Input (corresponds to single-end input / differential input)
- 10 Output LC filter free
- 11) Pop noise suppression circuit
- 12) Shutdown Function (use as mute at the same time) [low shutdown current = 0.01µA (Typ.)]
- 13) Contains protection circuit: output short, thermal shutdown, under voltage lockout (UVLO)

#### Applications

Mobile phone, Portable audio device, PND, DSC, Note-PC etc.

# ● Absolute Maximum Rating(Ta=+25°C)

Parameter	Symbol	Ratings	Unit
Power Supply Voltage	VDDmax / PVDDmax	7.0	V
Power Dissipation	Pd	690*	mW
Storage Temperature Range	Tstg	-55 <b>∼</b> +150	°C
SDNB Pin Input Range	V <sub>SDNB</sub>	-0.3~VDD+0.3	V
IN+, IN- Pin Input Range	V <sub>IN</sub>	-0.3~VDD+0.3	V

In case Ta=+25°C or more, 5.52 mW decrease per 1°C
 When mounting Rohm Typical Board 50.0mm×58.0mm (Material: Glass Epoxy)

#### Operation Range

Parameter	Symbol	Ranges	Unit
Temperature	Topr	-40 <b>~</b> +85	°C
Power Supply Voltage	VDD / PVDD	+2.5 ~ +5.5	V
ALC operating Power Supply Voltage	VDD <sub>ALC</sub> / PVDD <sub>ALC</sub>	+3.4 ~ +5.5	V
Common Mode Input Voltage Range	V <sub>IC</sub>	+0.5 ~ VDD-0.8	V

1/19

This product is not designed for protection against radioactive rays.

# ● Electrical Characteristic (Ta=+25°C, VDD=+3.6V, Unless specified otherwise)

Parameter		Cumbal		Limits		Unit	Conditions
		Symbol -	Min.	Тур.	Max.	Unit	Conditions
<all device=""></all>							
Circuit current (no signa	ıl)	I <sub>CC</sub>	1	3.3	6.6	mA	IC Active, No Load V <sub>SDNB</sub> = VDD
Circuit current (shutdow	n)	I <sub>SDN</sub>		0.01	2	μΑ	IC Shutdown V <sub>SDNB</sub> =GND
<audio feature=""></audio>							
Limit output power		Po	0.4	0.6	_	W	BTL, f=1kHz, R <sub>L</sub> =8Ω THD+N≦1% , *1, *2
Total harmonic distortio	n	T <sub>HD+N</sub>	_	0.2	1	%	BTL, fin=1kHz, $R_L$ =8 $\Omega$ $P_O$ =0.4W, *1
Maximum Gain		G <sub>MAX</sub>	11	12	13	dB	BTL, *1
ALC Limit level		$V_{LIM}$	+6	+7	+8	dBV	BTL, *1, *2
ALC Release level		$V_{REL}$	+4	+5	+6	dBV	BTL, *1, *2
Switching frequency		f <sub>OSC</sub>	150	250	350	kHz	
Start-up time		T <sub>ON</sub>	0.73	1.02	1.71	msec	
Audio input resistance		Ri	40	60	80	kΩ	Gain=12dB
<control terminal=""></control>							
SDNB terminal Threshold voltage	Н	V <sub>SDNBH</sub>	1.4	_	VDD	V	IC Active
	L	V <sub>SDNBL</sub>	0	_	0.4	V	IC Shutdown
SDNB terminal	Н	I <sub>SDBNH</sub>	12	24	36	μΑ	V <sub>SDNB</sub> =3.6V
Inflow Current	L	I <sub>SDNBL</sub>	-5	_	5	μΑ	V <sub>SDNB</sub> =0V

<sup>\*1</sup> Filter bandwidth for measurement: 400∼30kHz, LC filter for AC measurement: L=22μH / C=1μF, BTL: Voltage between A3,C3

#### ■Shutdown control

= Shuldown Control	
Control terminal	Conditions
SDNB	Conditions
Н	IC operation (active)
L	IC stop (shutdown)

#### ■ALC Parameter

ALC Parameter				
Attack Time (Typ.)	Release Time(Typ.)	Gain Switch Step (Typ.)		
~1ms/1dB @ fin=100Hz ~0.5ms/1dB @ fin=1kHz ~0.05ms/1dB @ fin=10kHz	560ms/1dB @ fin=100∼10kHz	±1dB		

The ALC automatically adjusts the audio output level, and a function that prevents the over output to the speaker. When ALC function is working, gain switches at zero-cross point of audio output normally. If the time that audio output reaches to zero-cross point is long, gain switches at about 1msec later (attack time), at about 25msec later (release time). So, attack time and release time will change at audio input frequency. ALC parameter is fixed. ALC operation doesn't correspond to noise of impulse.

Also, ALC limit level is independent type from power supply voltage (fixed type). When power supply voltage goes down during ALC operation, there will be a risk of generating distortion at the speaker output wave.

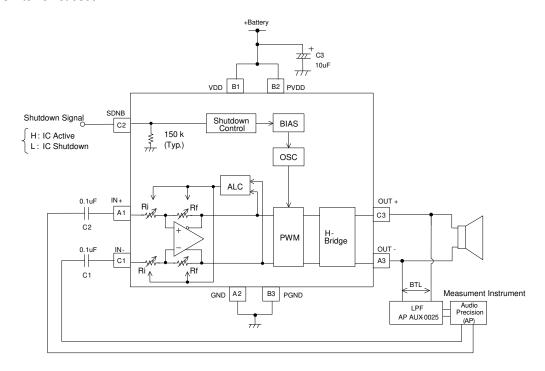
<sup>\*2</sup> The reference value when the device and each component is directly mounted to the Rohm typical board.

BD5465GUL Technical Note

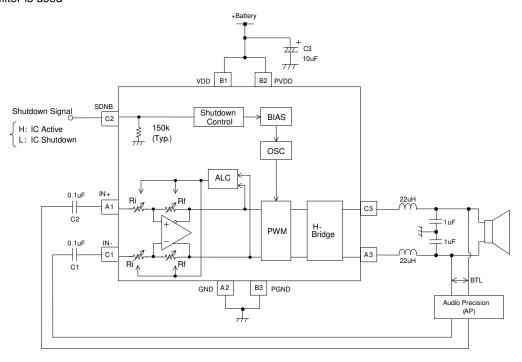
#### Measurement Circuit Diagram

<Audio Characteristics Method of Evaluation >

#### ■In case LC filter is not used



#### ■In case LC filter is used



Audio characteristics can be measured to insert LC filter between output pin and speaker load, if you don't have a measurement equipment for switching amplifier, like AUX-0025, Audio Precision.

Arrange the LC filter directly close to output pin.

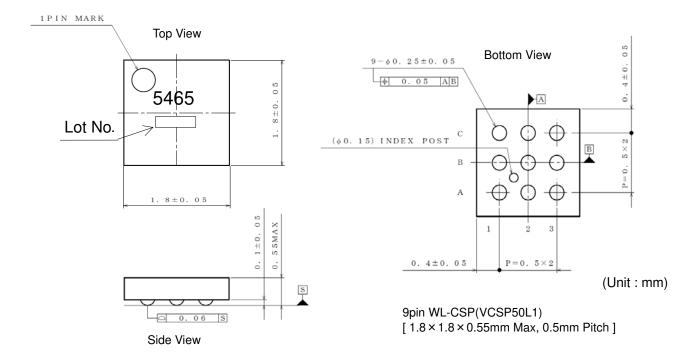
In case of L=22 $\mu$ H, C=1 $\mu$ F, cut off frequency becomes:

$$fc = \frac{1}{2\pi\sqrt{LC}} = \frac{1}{2\pi\sqrt{22\mu H \times 1\mu F}} \cong 34kHz$$

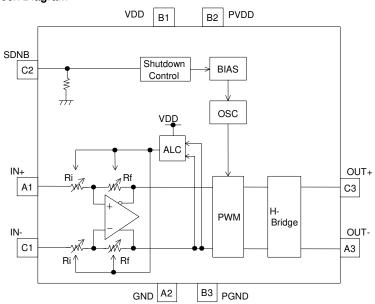
For Inductor L, please use huge current type.

(Reference)TDK: SLF12575T-220M4R0

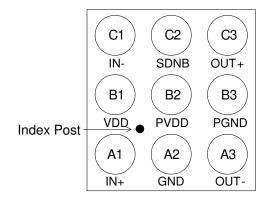
# External Dimension Diagram



# ●Block Diagram



# ● Pin Arrangement (Bottom View)



# ●Pin Explanation

Pin No.	Pin Name	Explanation	
A1	IN+	Audio differential input + terminal	
A2	GND	GND terminal (signal)	
A3	OUT-	Class-D BTL output - terminal	
B1	VDD	VDD terminal (signal)	
B2	PVDD	VDD terminal (power)	
В3	PGND	GND terminal (power)	
C1	IN-	Audio differential input - terminal	
C2	SDNB	Shutdown control terminal	
C3	OUT+	Class-D BTL output + terminal	

#### Application circuit example

SHORT the power supply pin VDD (B1), PVDD (B2) at board pattern, then use singleness power supply.

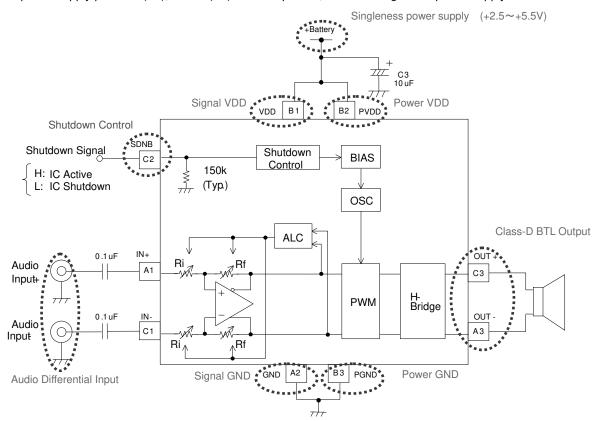


Fig1. Differential Input(With Input Coupling Capacitor)

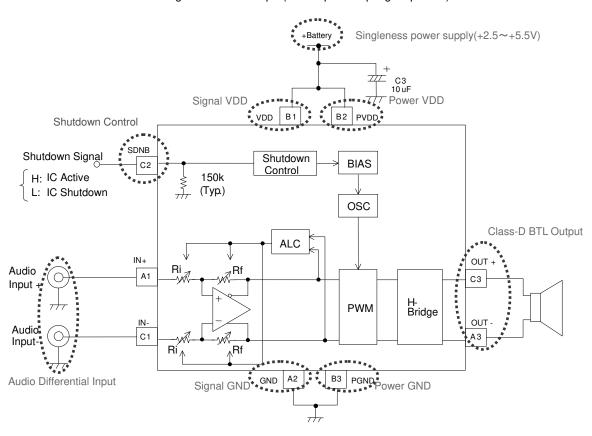


Fig2. Differential Input(Without Input Coupling Capacitor)

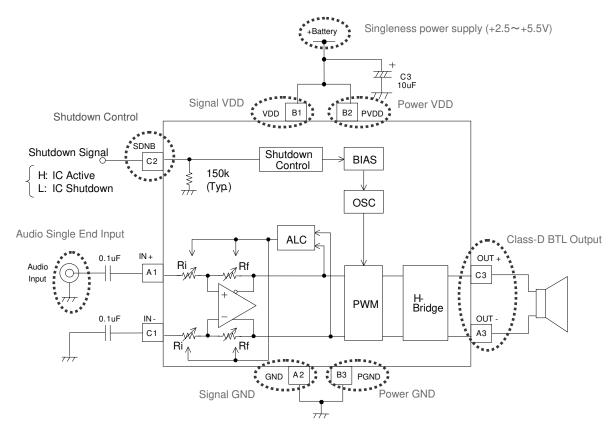


Fig3. Single end input (during IN+ input)

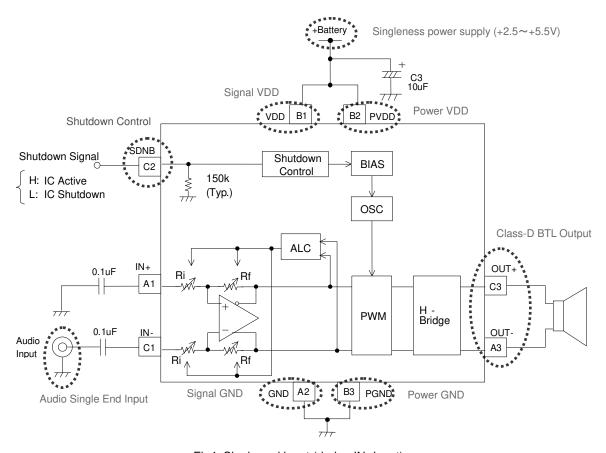


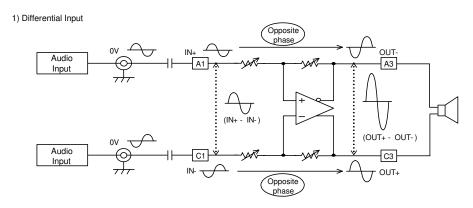
Fig4. Single end input (during IN- Input)

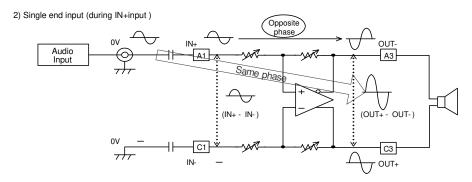
#### ● About the difference of differential input and single end input

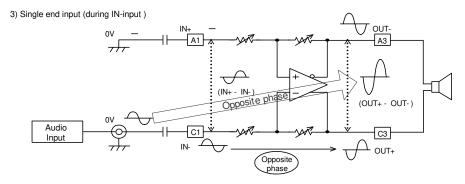
BD5465GUL uses full differential amplifier.

BD5465GUL is a Class-D amplifier, but, in relation to Audio Input and Output, is same with the conventional Class-AB amplifier. For simplicity purposes of the diagram, the Class-D amplifier output stage is omitted in the following explanation.

About the resistor, signal — on the diagram Gives meaning to changes of gain setting by means of ALC Control.







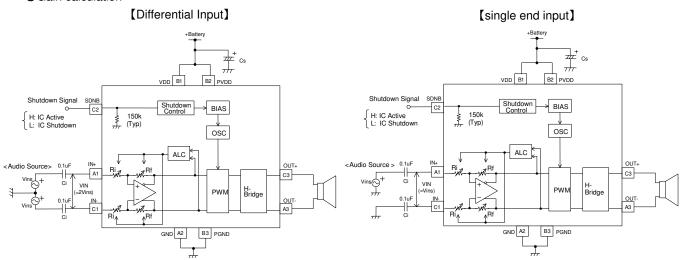
#### OAbout single end input

- Input is possible whether IN+ or IN- Pin.

  Don't make input pin open, through the input coupling capacitor, please connect to GND as seen on the example above. Audio input pin should make "mute" condition, not "open" condition when you don't input any signal.
- During single end input IN+ and IN-, there is a difference with the phase relation of input and output.
   Because of differential amplifier, if input (IN+ IN-), output(OUT+ OUT-), the audio input and output phase relation will become:

Phase	IN+ Input	IN- Input	
Audio Input ⇒ output (OUT+ - OUT-)	Same phase	Opposite phase	

#### OGain calculation



When Input Level is calculated at IC typical and audio source typical, when input coupling capacitor (Ci) value is large enough, every gain during the differential input and single end input will become:

Typical Input Level	Differential Output	Single End Output	
IC	Formula(1)		
Audio Source	Formula(2)	Formula(1)	

1. IC reference(Difference Input, Single End Input): Formula ①

VIN means the Input Voltage between IC Input Pin (IN+, IN-), VOUT means the output voltage between IC Output Pin (OUT+, OUT-). During differential input and single end input, the gain calculation formula at IC reference which includes ALC operation is written below:

Gain = 
$$20 \times \log |VOUT/VIN| = +12 \sim -3$$
 (Typ.) [dB] · · · Formula①

2. Audio Source reference(Differential Input): Formula ②

When the input level of audio source is Vins, the relation with the input voltage VIN between IC input pin is written below:

$$Vins = VIN / 2$$

During differential input, at audio source referece that includes ALC operation, gain calculation formula will become:

3. Audio Source reference (Single End Input) : Formula  $\ \ \textcircled{1}$ 

When the Input level of audio source is Vins, the relation with input voltage VIN between IC input pin (IN+,IN-) becomes:

$$Vins = VIN$$

During single end input, at the audio source that includes ALC operation, gain calculation formula becomes:

#### Audio Input Pin External LPF connection example

#### ■External LPF connection example

The connection example of  $1^{st}$  -order LPF which is formed at Resistor R<sub>LPF</sub> and Capacitor C<sub>LPF</sub>, to the Audio Input Pin IN+/- (A1, C1 Pin) is shown below. The cut frequency of input LPF, together with the single end input and differential input is written below:

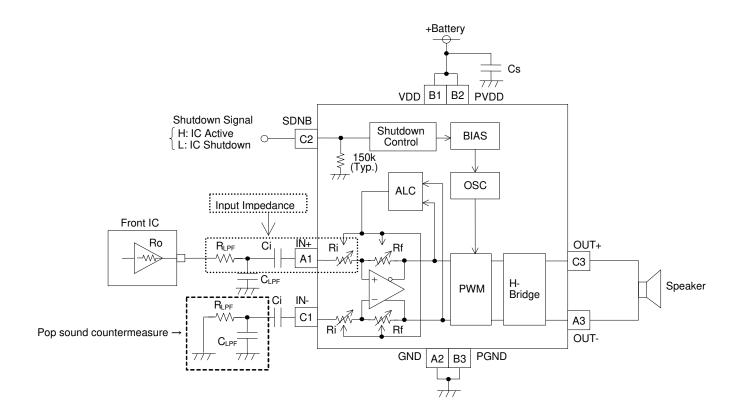
$$fc_{LPF} = 1 / (2 \times \pi \times R_{LPF} \times C_{LPF})$$
 [Hz]

Ex) 
$$f_{CLPF}=10kHz \Rightarrow C_{LPF}=0.01\mu F, R_{LPF}=1.59k\Omega$$

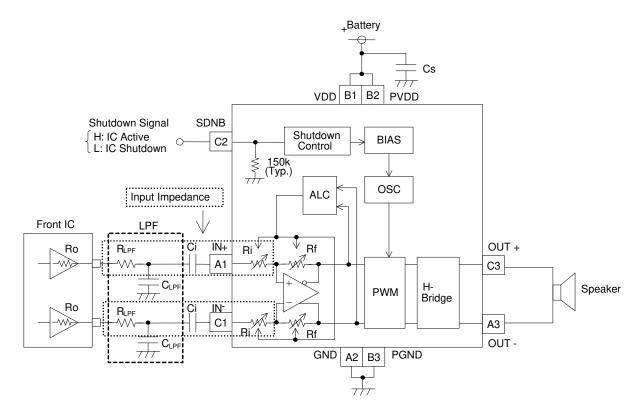
#### During single end input

When LPF is connected to audio input pin at single end input setting, at start-up characteristics of audio input pin IN+/-, during start-up with unbalance (power supply ON/OFF, or shutdown ON/OFF), there is a risk that POP sound will occur so please be careful.

When no audio input, and in order to prevent output noise, please make previous IC "mute" condition, not "open" condition. Please refer at the same time to POP Sound countermeasure example.



#### 2) Differential Input



#### ■Caution during External LPF Setting

External LPF Resistor  $R_{LPF}$  which is composed of IC input resistor Ri, forms input impedance. The bigger the resistor value of LPF resistor  $R_{LPF}$  the more it will decrease the gain.

When the input capacitor Ci has enough large capacity value, the relation among external LPF resistor R<sub>LPF</sub> and IC input resistor Ri and Gain will become:

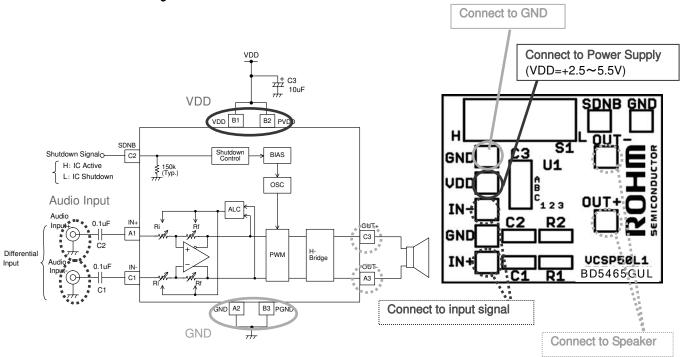
$$Gain = 20 \times log | Rf / (Ri + R_{LPF}) | [dB]$$

Input resistor Ri of BD5465GUL and resistor value of feedback resistor Rf will become the following below, during ALC operation, changes at ±1dB step, and becomes 16 stages switch specs.

```
#1. Ri=60k\Omega(Typ.), Rf=240k\Omega(Typ.)@Gain=12dB #2. Ri=66k\Omega(Typ.), Rf=234k\Omega(Typ.)@Gain=11dB #3. Ri=72k\Omega(Typ.), Rf=228k\Omega(Typ.)@Gain=10dB \downarrow #15. Ri=167k\Omega(Typ.), Rf=133k\Omega(Typ.)@Gain=-2dB #16. Ri=176k\Omega(Typ.), Rf=124k\Omega(Typ.)@Gain=-3dB
```

Also with the driver ability of previous IC step, after checking, constant setting of external LPF and Resistor R<sub>LPF</sub>.

#### ● Evaluation Board Circuit Diagram



<sup>\*</sup> Power Supply terminals VDD(B1), PVDD(B2) are SHORT in the board pattern and use a single power.

#### ● Evaluation Board Parts List

aluation board rans List							
Qty.	Item	Description	SMD Size	Manufacturer/ Part Number			
2	C1, C2	Capacitor, 0.1μF	0603	Murata GRM188R71C104KA01D			
1	C3	Capacitor, 10μF	A (3216)	ROHM TCFGA1A106M8R			
1	S1	Slide Switch	4mm X 10.2mm	NKK SS-12SDP2			
1	U1	IC, BD5465GUL, Mono Class-D Audio Amplifier	1.8mm X 1.8mm WLCSP Package	ROHM BD5465GUL			
1	PCB1	Printed-Circuit Board, BD5465GUL EVM	_	_			

#### About the external part

①Input coupling capacitor (C1, C2)

Input coupling capacitor is 0.1µF.

Input impedance during maximum gain 12dB is  $60k\Omega$  (Typ.). A high-pass filter is composed by the input coupling capacitor and the input impedance.

Cut-off frequency "fc" by the formula below, through input coupling capacitor C1(=C2) and input impedance Ri.

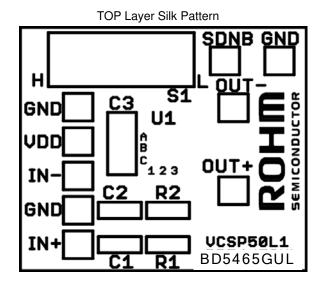
$$fc = \frac{1}{2\pi \times Ri \times C1} Hz$$

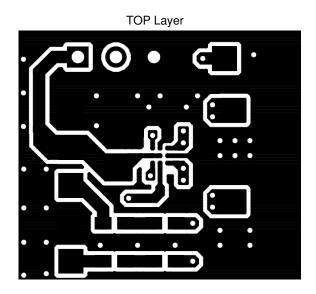
In case of Ri=60k $\Omega$ , C1(=C2)=0.1 $\mu$ F, cut-off frequency is about 26.5Hz

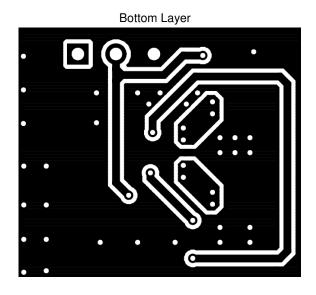
#### 2) Power Supply Decoupling Capacitor (C3)

Power Supply Decoupling Capacitor is 10uF. When the capacity value of Power Supply Decoupling Capacitor is made small, it will have an influence to the audio characteristics. When making it small, be careful with the audio characteristics at actual application. ESR (equivalent series resistor) is low enough; please use capacitor with capacity value of 1µF or more.

# ●Evaluation Board PCB Layer







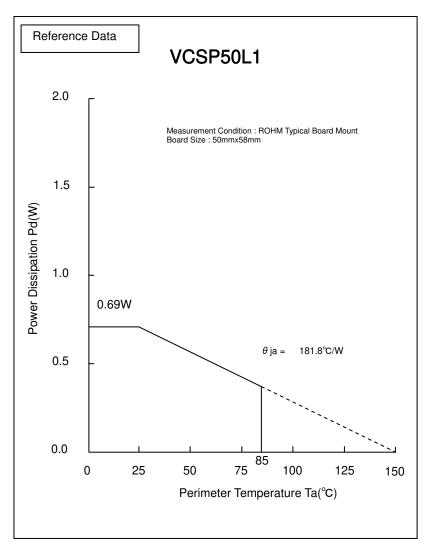
#### About IC Thermal Design

The IC Characteristics has a big relation with the temperature that will be used, to exceed the maximum tolerance junction temperature, can deteriorate and destroy it. Instant destruction and long-time operation, from these 2 standpoints, there is a need to be careful with regards to IC thermal. Please be careful with the next points.

The absolute maximum rating of IC shows the maximum junction temperature  $(Tj_{MAX})$  or the operation temperature range (Topr), so refer to this value, use Pd-Ta characteristics (Thermal reduction ratio curve). If input signal is excessive at a state where heat radiation is not sufficient, there will be TSD(Thermal Shutdown)

For TSD, the chip temperature operates at around 180°C, releases if it's around 120°C or less. Since the aim is to prevent damage on the chip, please be careful because the long use time at the vicinity where TSD operates can deteriorate the dependency of the IC.

#### Thermal Reduction Ratio Curve

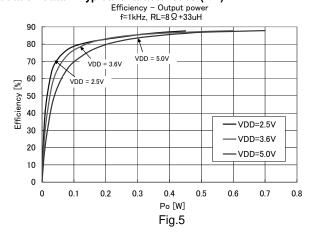


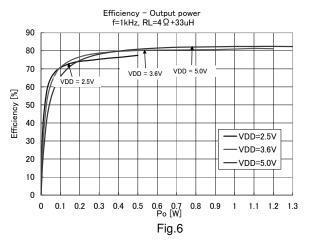
Note: This value is the real measurement, but not the guaranteed value.

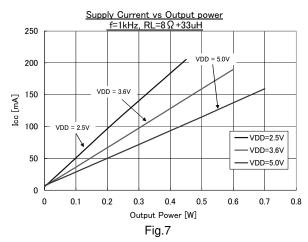
The value of power dissipation changes based on the board that will be mounted.

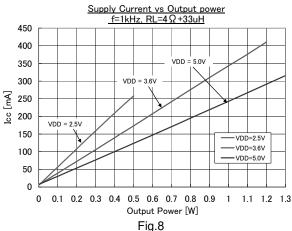
The power dissipation of main IC during the heat dissipation design of many mounted boards, will become bigger than the value of the above graph.

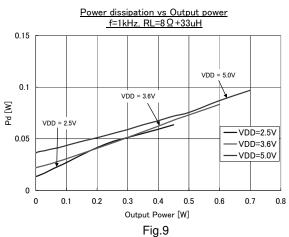
#### ● Evaluation data – Typical characteristics (1/4)

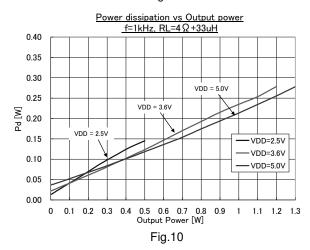


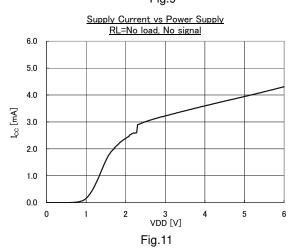


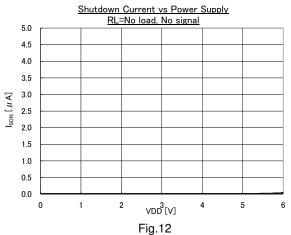




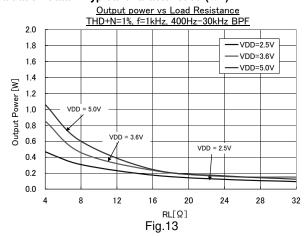


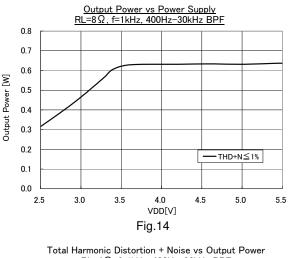


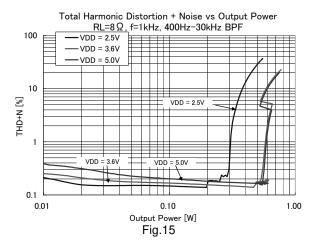


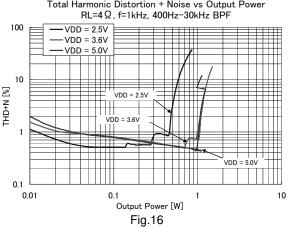


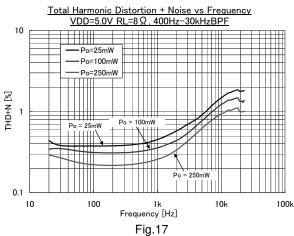
#### ● Evaluation data – Typical characteristics (2/4)

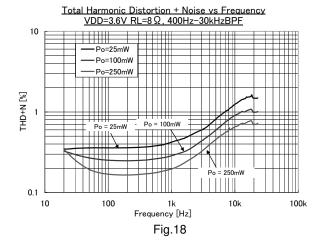




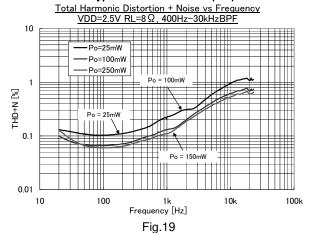


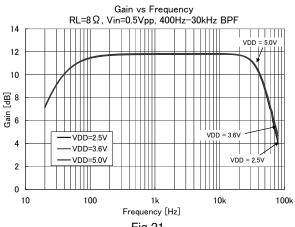


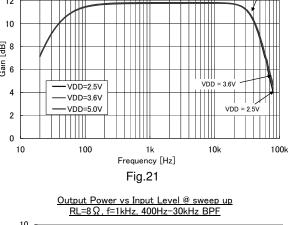


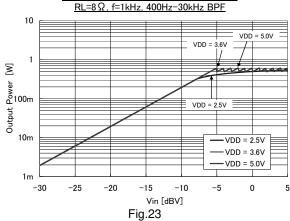


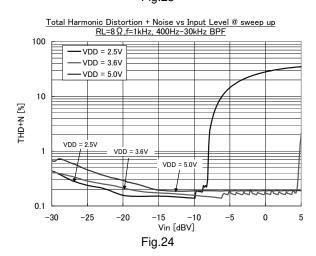
# ●Evaluation data – Typical characteristics (3/4)

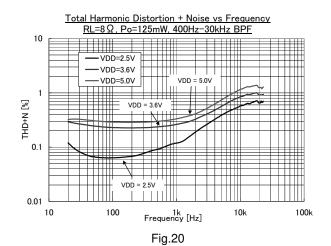


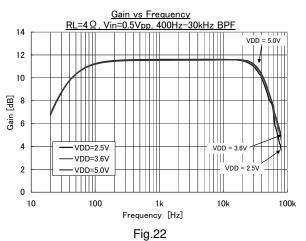




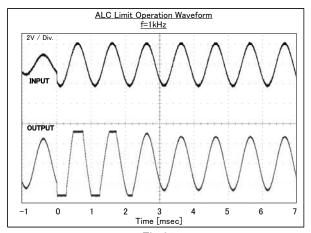








# ● Evaluation data – Typical characteristics (4/4)





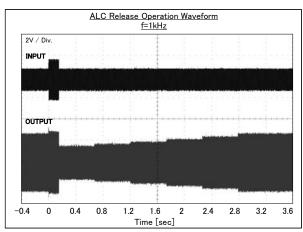


Fig.26

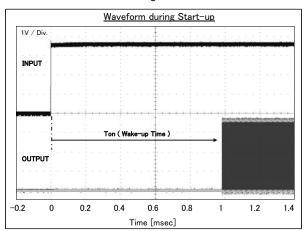


Fig.27

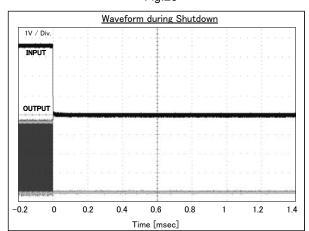


Fig.28

#### Notes for use

- (1) The numerical value and the data of the mention are a design representative value and are not the one which guarantees
- (2) It is convinced that it should recommend application circuit example but in case of use, we request the confirmation of the characteristic more sufficiently. When changing an external part fixed number and becoming use, it considers sprawl of the external part and our company's LSI including the transition characteristic in addition to the stillness characteristic and so on, see and fix an enough margin.
- (3) Absolute maximum ratings

This IC may be damaged if the absolute maximum ratings for the applied voltage, temperature range, or other parameters are exceeded. Therefore, avoid using a voltage or temperature that exceeds the absolute maximum ratings. If it is possible that absolute maximum ratings will be exceeded, use fuses or other physical safety measures and determine ways to avoid exceeding the IC's absolute maximum ratings.

- (4) GND terminal's potential
  - Try to set the minimum voltage for GND terminal's potential, regardless of the operation mode.
- (5) Shorting between pins and mounting errors

When mounting the IC chip on a board, be very careful to set the chip's orientation and position precisely. When the power is turned on, the IC may be damaged if it is not mounted correctly. The IC may also be damaged if a short occurs (due to a foreign object, etc.) between two pins, between a pin and the power supply, or between a pin and the GND.

- (6) Operation in strong magnetic fields
  - Note with caution that operation faults may occur when this IC operates in a strong magnetic field.
- (7) Thermal design

Ensure sufficient margins to the thermal design by taking in to account the allowable power dissipation during actual use modes, because this IC is power amplifier. When excessive signal inputs which the heat dissipation is insufficient condition, it is possible that thermal shutdown circuit is active.

- (8) Thermal shutdown circuit
  - This product is provided with a built-in thermal shutdown circuit. When the thermal shutdown circuit operates, the output transistors are placed under open status. The thermal shutdown circuit is primarily intended to shut down the IC avoiding thermal runaway under abnormal conditions with a chip temperature exceeding T<sub>imax</sub>=+150°C, and is not intended to protect and secure an electrical appliance.
- (9) Load of the output terminal

This IC corresponds to dynamic speaker load, and doesn't correspond to the load except for dynamic speakers. When using speaker load  $8\Omega$  or less (especially  $4\Omega$ ), there will be a risk of generating distortion at the speaker output wave form during ALC limit operation.

- (10) The short protection of the output terminal
  - This IC is built in the short protection for a protection of output transistors. When the short protection is operated, output terminal become Hi-Z condition and is stopped with latch. Once output is stopped with latch, output does not recover automatically by canceling the short-circuiting condition. The condition of stopping with latch is cancelled, when power supply or mute signal is turned off and turned on again.
- (11) Operation Range

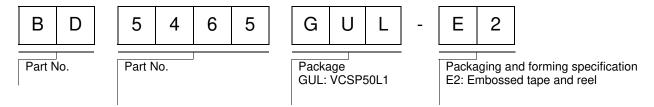
The rated operating power supply voltage range (VDD=+2.5V~+5.5V) and the rated operating temperature range (Ta=-40°C ~+85°C) are the range by which basic circuit functions is operated. Characteristics and rated output power are not guaranteed in all power supply voltage ranges or temperature ranges.

- (12) Electrical Characteristics
  - Every audio characteristics list of the limit output power, total harmonic distortion, maximum gain, ALC limit level, ALC release level etc. shows the typical characteristics of the device, highly dependent to the board lay-out, parts to be used, power supply. The value when the device and each component are directly mounted to the board of Rohm.
- (13) Power Supply

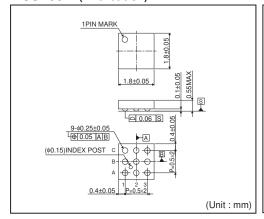
Since the Power Supply Pin for signal (VDD) and power supply for Power (PVDD) is SHORT at internal, short the board pattern, then use a single power supply. Also, the power supply line of class-D speaker amplifier flows big peak energy. It will influence the audio characteristics based on the capacity value of power supply decoupling capacitor, arrangement. For the power supply decoupling capacitor, please arrange appropriately the low capacity (1µF or more) of ESR (equivalent series resistor) directly near to IC Pin.

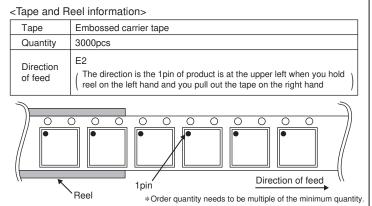
- (14) ALC (Automatic Level Control) Function
  - The ALC automatically adjusts the audio output level, and a function that prevents the over output to the speaker. When ALC function is working, gain switches at zero-cross point of audio output normally. If the time that audio output reaches to zero-cross point is long, gain switches at about 1msec later (attack time), at about 25msec later (release time). So, attack time and release time will change at audio input frequency. ALC parameter is fixed. ALC operation doesn't correspond to noise of impulse.
  - Also, ALC limit level is independent type from power supply voltage (fixed type). When power supply voltage goes down during ALC operation, there will be a risk of generating distortion at the speaker output wave.

# Ordering part number



# VCSP50L1(BD5465GUL)





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(Note1) Medical Equipment Classification of the Specific Applications

1	1		
JAPAN	USA	EU	CHINA
CLASSⅢ	CLACCIII	CLASS II b	СГУССШ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

# **Precautions Regarding Application Examples and External Circuits**

- If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

#### **Precaution for Foreign Exchange and Foreign Trade act**

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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